PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PATI881128

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
ST. CLOUD CAPITAL PARTNERS IV SBIC, L.P.	11/01/2022

RECEIVING PARTY DATA

Company Name:	ATOMICA CORP.
Street Address:	75 Robin Hill Road
City:	Goleta
State/Country:	CALIFORNIA
Postal Code:	93117

PROPERTY NUMBERS Total: 58

Property Type	Number
Patent Number:	6812061
Patent Number:	7057245
Patent Number:	7141080
Patent Number:	7582969
Patent Number:	7528691
Patent Number:	7233048
Patent Number:	7276991
Patent Number:	7569926
Patent Number:	7548145
Patent Number:	7785913
Patent Number:	7533792
Patent Number:	7872432
Patent Number:	7812703
Patent Number:	7807547
Patent Number:	7462931
Patent Number:	7550778
Patent Number:	7675162
Patent Number:	7688167
Patent Number:	7968986
Patent Number:	7893798

Property Type	Number
Patent Number:	7972683
Patent Number:	7864006
Patent Number:	8088651
Patent Number:	7759218
Patent Number:	7944113
Patent Number:	7960208
Patent Number:	8245391
Patent Number:	8541735
Patent Number:	8690830
Patent Number:	8343791
Patent Number:	8466760
Patent Number:	8264307
Patent Number:	8338283
Patent Number:	8871500
Patent Number:	8822207
Patent Number:	8736081
Patent Number:	8847373
Patent Number:	9274180
Patent Number:	9372185
Patent Number:	9315375
Patent Number:	9388037
Patent Number:	9162878
Patent Number:	9156679
Patent Number:	9330874
Patent Number:	9302905
Patent Number:	9953787
Patent Number:	9533877
Patent Number:	10388468
Patent Number:	10011478
Patent Number:	10291332
Patent Number:	10302871
Patent Number:	10804850
Patent Number:	10955336
Patent Number:	10826153
Patent Number:	11305982
Patent Number:	11258425
Patent Number:	11309837
Application Number:	17200954

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Mrs. JULIANNE FRANCIS
SIGNATURE:	/Mrs. JULIANNE FRANCIS/
DATE SIGNED:	03/12/2025

Total Attachments: 5

source=20250312_CENFG001_Security-Interest-Release#page1.tiff
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RELEASE OF SECURITY INTEREST

This Release of Security Interest is Effective November 1, 2022, by ST. CLOUD CAPITAL PARTNERS IV SBIC, L.P., a Delaware limited partnership ("Grantee") in favor of ATOMICA CORP., a Delaware corporation ("Grantor"), with its principal place of business located at 75 Robin Hill Road, Goleta, California 93117.

Recitals

WHEREAS Grantor granted to Grantee a security interest in substantially all of the assets of Grantor including all right, title and interest of Grantor in, to and under all now owned and hereafter acquired Patents (as defined in the Security Agreement), and all products and proceeds thereof, to secure payment and performance of the Obligations, including the patents listed in Schedule 1.

WHEREAS Grantee agrees to release its security interest.

AGREEMENT

Now therefore, Grantee agrees that it terminates and releases its security interest and reassigns to Grantor, without warranty or recourse, all interest of Grantee in the patents listed in Schedule 1.

Grantee:

ST. CLOUD CAPITAL PARTNERS IV SBIC, L.P.

Name: ROBERT LAUTZ

Title: M.P

SCHEDULE 1

Patents

Patent Description	Patent Number	Registration Date	Jurisdiction
Method and apparatus for assembling an array of micro-devices	6812061	11/2/2004	US
Method and apparatus for assembling an array of micro-devices	7057245	6/6/2006	US
Method and apparatus for assembling an array of micro-devices	7141080	11/28/2006	US
Hermetic interconnect structure and method of fabrication	7582969	9/1/2009	US
Dual substrate electrostatic MEMS switch with hermetic seal and method of manufacture	7528691	5/5/2009	US
Trench plating process and apparatus for through hole vias	7233048	6/19/2007	US
Multiple switch MEMS structure and method of manufacture	7276991	10/2/2007	US
Wafer level hermetic bond using metal alloy with raised feature	7569926	8/4/2009	US
Hysteretic MEMS thermal device and method of manufacture	7548145	6/16/2009	US
System and method for forming moveable features on a composite substrate	7785913	8/31/2010	US
Elastic interface for wafer bonding apparatus	7533792	5/19/2009	US
MEMS thermal device with slidably engaged tether and method of manufacture	7872432	1/18/2011	US
MEMS device using NiMn alloy and method of manufacture	7812703	10/12/2010	US
Wafer bonding material with embedded rigid particles	7807547	10/5/2010	US
Indented lid for encapsulated devices and method of manufacture	7462931	12/9/2008	US
System and method for providing access to an encapsulated device	7550778	6/23/2009	US
Interconnect structure using	7675162	3/9/2010	US

through wafer vias and method of fabrication			
Contract electrodes for microdevice and etch method of manufacture	7688167	3/30/2010	US
Lid structure for microdevice and method of manufacture	7968986	6/28/2011	US
Dual substrate MEMS plate switch and method of manufacture	7893798	2/22/2011	US
Wafer bonding material with embedded conductive particles	7972683	7/5/2011	US
MEMS plate switch and method of manufacture	7864006	1/4/2011	US
System and method for providing access to an encapsulated device	8088651	1/3/2012	US
Indented lid for encapsulated devices and method of manufacture	7759218	7/20/2010	US
Hysteretic MEMS thermal device and method of manufacture	7944113	5/17/2011	US
Wafer level hermetic bond using metal alloy with raised feature	7960208	6/14/2011	US
Hysteretic MEMS two-dimensional thermal device and method of manufacture	8245391	8/21/2012	US
Inlaid optical material and method of manufacture	8541735	9/24/2013	US
In-plane electromagnetic MEMS pump	8690830	4/8/2014	US
Plating process and apparatus for through wafer feature	8343791	1/1/2013	US
Configurable power supply using MEMS switch	8466760	6/18/2013	US
Dual substrate MEMS switch and method of manufacture	8264307	9/11/2012	US
Method and apparatus for applying thin liquid films	8338283	12/25/2012	US
MEMS particle sorting actuator and method of manufacture	8871500	10/28/2014	US
Cartridge for MEMS particle sorting system	8822207	9/2/2014	US
Wafer level hermetic bond using metal alloy with keeper layer	8736081	5/27/2014	US
Exothermic activation for high vacuum packaging	8847373	9/30/2014	US

Microfabricated magnetic field transducer with fluxguide	9274180	3/1/2016	US
MEMS particle sorting actuator and method of manufacture	9372185	6/21/2016	US
Method using glass substrate anodic bonding	9315375	4/19/2016	US
Device using glass substrate anodic bonding	9388037	7/12/2016	US
Wafer level hermetic bond using metal alloy with wetting layer	9162878	10/20/2015	US
Method and device using silicon substrate to glass substrate anodic bonding	9156679	10/13/2015	US
Solder bump sealing method and device	9330874	5/3/2016	US
Method for forming microfabricated structure	9302905	4/5/2016	US
Dual substrate electrostatic MEMS switch with multiple hinges and method of manufacture	9953787	4/24/2018	US
Anodic bonding of dielectric wafers	9533877	1/3/2017	US
Contact material for MEMS devices	10388468	8/20/2019	US
Thermocompression bonding with raised feature	10011478	7/3/2018	US
Self-aligned silicon fiber optic connector	10291332	5/14/2019	US
Method for forming microfabricated structure	10302871	5/28/2019	US
Gas sensor using MM wave cavity	10804850	10/13/2020	US
Gas sensor using etalon	10955336	3/23/2021	US
Resonant cavity for MM wave filter	10826153	11/3/2020	US
Eight spring dual substrate MEMS plate switch and method of manufacture	11305982	4/19/2022	US
Microfabricated notch filter	11258425	2/22/2022	US
Resonant cavity for MM wave filter	11309837	4/19/2022	US
Wafer level hermetic bond using metal alloy with raised feature	JP5244609	12/4/2013	Japan
Wafer level hermetic bond using metal alloy with raised feature	EP1961036	8/27/2008	Europe

Schedule 1

Patent Applications

Patent Application Description	Patent Application Number	Patent Application Date	Jurisdiction
MEMS DUAL SUBSTRATE SWITCH WITH MAGNETIC ACTUATION	17/200954	7/1/2021	US